

ABSTRACT

A device manufacturing method using lithographic apparatus, in which method a patterned beam of radiation is projected on to a target portion of a substrate. Prior to exposing the substrate to the patterned beam of radiation a beam of compensating radiation is irradiated on to a predetermined area of the substrate, the beam of compensating radiation having an intensity which varies across said predetermined area. In the described embodiment the beam of compensating radiation is applied to an annular edge region of the substrate and has an intensity which is tilted across the cross-section of the beam so as to increase or decrease in intensity towards the edge of the substrate. This is done to improve the critical dimension (CD) uniformity across the substrate.